ABSTRACT

Provided is a semiconductor package having high electric reliability. The semiconductor package includes a lower sub-semiconductor package including a lower semiconductor chip and a lower mold layer on the lower semiconductor chip and having a mold via hole, an upper sub-semiconductor package including an upper semiconductor chip, a filling layer that is between the lower sub-semiconductor package and the upper sub-semiconductor package, a connection via in the mold via hole that penetrates the lower mold layer and the filling layer and electrically connects the lower sub-semiconductor package to the upper sub-semiconductor package. The filling layer includes an extending part of the filling layer that extends into the mold via hole of the filling layer from a portion having a higher level than a top surface of the lower mold layer.

[FIG. 1A]